



PK946(v1.0) January 10, 2018

# 100% Material Declaration Data Sheet for Spartan-7 FGGA484

Average Weight : 1.9920 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight ( in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00		<b>0.030589</b>	<b>1.536%</b>
					0.030589	
Die Attach Material	Silver	7440-22-4	74.00		0.004319	<b>0.293%</b>
	Bismaleimide monomer	trade secret	15.00		0.000876	
	Methacrylate resin	trade secret	7.50		0.000438	
	Additive	trade secret	3.00		0.000175	
	Proprietary	trade secret	0.50		0.000029	
Mold Compound					<b>0.858780</b>	<b>43.111%</b>
	Epoxy Resin A	Trade secret	3.00		0.025763	
	Epoxy Resin B	Trade secret	3.00		0.025763	
	Phenol Resin	Trade secret	3.00		0.025763	
	Silica(Amorphous) A	60676-86-0	72.45		0.622186	
	Silica(Amorphous) B	7631-86-9	15.00		0.128817	
	Metal Hydroxide	Trade secret	3.00		0.025763	
Carbon black	1333-86-4	0.55		0.004723		
Copper Wire					<b>0.005863</b>	<b>0.294%</b>
	Copper	7440-50-8	98.08		0.005750	
	Palladium	7440-05-3	1.80		0.000106	
Solder Ball	Gold	7440-57-5	0.12		0.000007	
					<b>0.404317</b>	<b>20.297%</b>
	Tin	7440-31-5	96.50		0.390166	
Substrate	Silver	7440-22-4	3.00		0.012130	
	Copper	7440-50-8	0.50		0.002022	
					<b>0.686614</b>	<b>34.469%</b>
	Solder mask	trade secret	3.77		0.025872	
	BT Core	trade secret	45.13		0.309876	
	Continuous Filament Fiber Glass	65997-17-3	18.10		0.124277	
	Gold	7440-57-5	1.16		0.007951	
	Nickel	7440-02-0	7.12		0.048887	
Copper Foil	7440-50-8	7.27		0.049889		
Copper plating	7440-50-8	12.87		0.088388		
PrepregGHPL830NXA	N/A	4.58		0.031474		

## Revision History

Date	Version	Description of Revisions
1/10/2018	1.0	Initial Xilinx release.